



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kinsman et al.

Serial No.: 09/917,127

Filed: July 27, 2001

For: METHOD FOR FABRICATING A
CHIP SCALE PACKAGE USING WAFER
LEVEL PROCESSING AND DEVICES
RESULTING THEREFROM

Confirmation No.: 3326

Examiner: M. Trinh

Group Art Unit: 2822

Attorney Docket No.: 2269-3572.1US
(97-1243.01/US)

Notice of Allowance Mailed:

January 26, 2004

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OK. to
ENTER
312-Amendment
M.T. 5/17/04

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Specification begin on page 2 of this paper.

Remarks begin on page 3 of this paper.